

Solid Dielectric Task Force

Hyatt Regency Denver Convention Center
Monday, Sept. 28, 2009

Chairman: Chris Ambrose
Secretary: François Soulard

The meeting was called to order. Self-introductions were made and the attendance sheet was routed. There were 17 Members out of 25, 3 excused, and 21 Guests. It was mentioned that Ed Steele has left the industry.

The mandatory IEEE Patent slides, including the letter of assurance, were presented. There were no comments or concerns brought up at this time.

The minutes from the last meeting were presented and approved.

The format of the draft sections of the SDTF report developed since the last meeting were displayed, and there were no significant comments.

General discussion

Section 1 – Definition/Scope (Chris Ambrose)

Section 2 - Materials (Nenad Uzelac)

- address the source of the pictures of the document
- consult Matt and Jody to confirm
- FS to get the Paper Template to start using it
- Composite material like porcelain and foam (Harry Hirz will help)

Section 3 – Applications and Environmental Conditions (Medium Voltage only) (Larry Putman)

- a. Application and environmental
 - C37.100-1 conditions shall apply
 - Larry Putman will correct his document for exposure to chemical env.
- b. Accelerated sealing lift test
 - done
- c. Thermal cycle withstand test
 - done
- d. UV resistance
 - done
- e. Salt fog aging test
 - done

Section 4 – Testing methods (Frank Muench)

- refer to TEST MATRIX SUMMERY .xls
- add std IEEE-592

Section 5 – Relevant Standards (Gerard Schoonenberg)

- These should address the end products, rather than the component materials.

Section 6 – Reference list (white papers) (Gerard Schoonenberg)

Section 7 - Appendix / Annex: (Chris Ambrose - with input from All)

- Requested input from Task Force on suggested products for testing and measurements, as well as relevant case studies.

Develop plans to bring the paper to conclusion, with presentation to RODE at the Spring or Fall meeting, as appropriate.

The chair recommended that small groups be established to work on some of the sections

Nenad (Materials), with Harry Hirz & Tim Taylor

Larry Putman (Apps & Environ) , with Frank DeCesaro and Mike LaBianco

Frank Muench (Testing), Frank DeCesaro & ?

Need to ask RODE about rights to illustrations used in report.

Next meetings - Sheraton Myrtle Beach, SC (Conv. Ctr.), April 25 – 29, 2010

- Las Vegas, Fall 2010

A meeting for the “small groups” was scheduled for Wednesday after lunch.

Adjourned.

Respectfully submitted,

Chris Ambrose
Chair, SDTF

Solid Dielectric Task Force (Supplemental Meeting for the Small Groups)

Hyatt Regency Denver Convention Center

Wednesday, Sept. 30, 2009

This informal meeting was held in the first part of the 1:30 PM time slot to follow-up on issues raised at the SDTF meeting.

Discussed the issue of the need to secure releases for illustrations used in the report, particularly in Nenad's section.

Steve Meiners will draft a "To Whom it May Concern" letter to the respective manufacturers, seeking release to use their pictures in the report document.

In Larry's group, it was mentioned that the format should be brought in line with C37.100.1.

Mike will create a survey of users.

Frank Muench & Frank DeCesaro will work to expand the testing matrix.

In relevant standards, it was determined that the stress should be placed on the end products, not the component materials.

It was determined that more IEEE and ASTM standards should be included to parallel the IEC standards shown.

Frank Muench and Frank DeCesaro will solicit input from within their organization.

Chris Ambrose once again requested input materials for inclusion in the Annex.

All sub-groups should submit their updates to the Chair by the end of January 2010.

The meeting was adjourned.

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